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Core model of the electronics domain

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

CORE MODEL OF THE ELECTRONICS DOMAIN

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International Standard IEC 62016 has been prepared by IEC technical committee 93: Design automation.

The document was released by the feeder organization, Government Electronics and Information Technology Association, a sector of the Electronic Industries Alliance (EIA), for committee draft comment, and review by members of IEC TC93 1.

The text of this standard is based on the following documents:

FDIS	Report on voting
93/172/FDIS	93/176/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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This standard does not follow the rules for the structure of International Standards given in the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until 2012-07. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

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INTRODUCTION

The Core Model of the electronics domain provides a common basis for design information handled by CAD systems within the electronic domain. It is the purpose of this model to provide a conceptual representation of the electronics domain, so that the compliant CAD systems handle a similar set of concepts, thus making inter-communication, sharing and exchange of design information a much easier task. It is not the purpose of this model to describe implementation details or to provide a data representation of electronics domain information.

The Core Model of the electronics domain, Edition 1.0, is referred to as the “Core Model” throughout this document. The Core Model, in part, has been created by enhancing the industry connectivity consensus model, EDIF CFI DR Alignment Model Version 1.0 (www.edif.org).

The chosen description language for this Core Model is EXPRESS, as defined by ISO 10303-11.

It is necessary to describe the Core Model as an information model in order to provide a formal definition of the design information that shall be recognized by the compliant CAD systems. The benefits of a formal description derive from its ability to provide an unambiguous representation of concepts, attributes and relationships, and the global rules and constraints that may be applied. By having such a description, it is possible to check the consistency and the correctness of the model as well as to provide a reliable starting-point for further development. It also facilitates the design of correct electronics CAD implementations based on this Core Model, as the actual implementation methods can be checked against the model.

This Core Model includes connectivity, hierarchy and design information for the electronics domain. Future parts of this Core Model standard may be extended to include other categories of information (for example, *cell_representation*, schematic representation, the PCB domain, symbols and display information).

In order to facilitate the creation of other parts of this Core Model standard, some objects have been used in this Core Model to facilitate support for other parts of the electronics domain. There are two types of such objects.

- Entities, such as *cell_representation*, are important concepts that provide support for defining other Core Model parts.
- Constraints: Some of constraints of this Core Model use conditions that are always true. They have been written in this way in order to ensure that they remain valid when the model is extended.

CORE MODEL OF THE ELECTRONICS DOMAIN

1 Scope and object

This International Standard provides the semantics definitions for the following categories of information related to electronic circuit designs. Each category of design information is modelled as an EXPRESS schema.

The Core Model consists of 10 schemas. Each of them is presented in this document as a separate chapter. At the beginning of each chapter, a description of the corresponding schema is provided.

- The *hierarchy_model* schema describes the hierarchical information of a cell, i.e. the way a cell may be divided into other cells.

A circuit may be divided into cells which, in turn, may be further subdivided into other cells, thus creating a hierarchy. The hierarchy information describes the cells, the possible cell representations and their instances.

- The *design_hierarchy_model* schema describes the annotation on an occurrence hierarchy.

The definition of a design requires that specific representations (views) of design objects in the hierarchy are selected. This unambiguously creates a configured design hierarchy. This concept is similar to the configuration of a design in VHDL and is related to view selection mechanisms of other electronics design domain information models in industry. The design hierarchy identifies top-level design cells and may provide annotated design-specific data into the elaborated hierarchy.

- The *connectivity_view_model* schema describes the connectivity information of a cell.

This describes the way in which the circuits are connected in order that information or energy may flow from one part of a design or product to another. The Core Model subdivides this information into

- the *logical_connectivity_model* schema which describes the connectivity for a given level of a hierarchy.

Logical connectivity information describes the bit level, abstract electrical connectivity for a given level of a hierarchy, in terms of signals and signal groups.

- the *connectivity_structure_model* schema which describes the structural connectivity of a connectivity view.

Structural connectivity information describes the connectivity, for a given level of a hierarchy, from the structural point of view. The structural connectivity is specified in terms of busses, nets and rippers. Such a structural representation is used to provide support for physical implementation and annotation.

- The *library_model* schema describes the technology information contained in a library, as well as the reusable objects and data.

A library provides a means of grouping cell definitions. A library may be used to group other classes of reusable objects and information as well. Information in a library may be related in terms of technology information.

- The *information_base_model* schema describes the information in an information base.

The *information_base* describes the kind of information that can be found directly in an information base.

In addition, the following information is also included in the model.

- The *design_management_model* schema provides the design management information. This information is needed to trace back to the source or the owner of the data.
- The *documentation_model* schema describes the documentation provided for an object.
- The *support_definition_model* schema contains the definition of some auxiliary entities, types and functions that are used by several schemas.

Names of objects used in this Core Model standard were chosen to be the same as the names of the similar objects and concepts in existing electronics domain information models wherever possible.

2 Reference documents

IEC 61690-1:2000, *Electronic design interchange format (EDIF) – Part 1: Version 3.0*

IEC 61690-2:2000, *Electronic design interchange format (EDIF) – Part 2: Version 4.0*

ISO 13030-11:1994, *Industrial automation systems and integration – Product representation and exchange – Part 11: Description methods: The EXPRESS-I language reference manual*